

# Infusion Doping for USJ Applications with Gas Cluster Ion Beam Processing



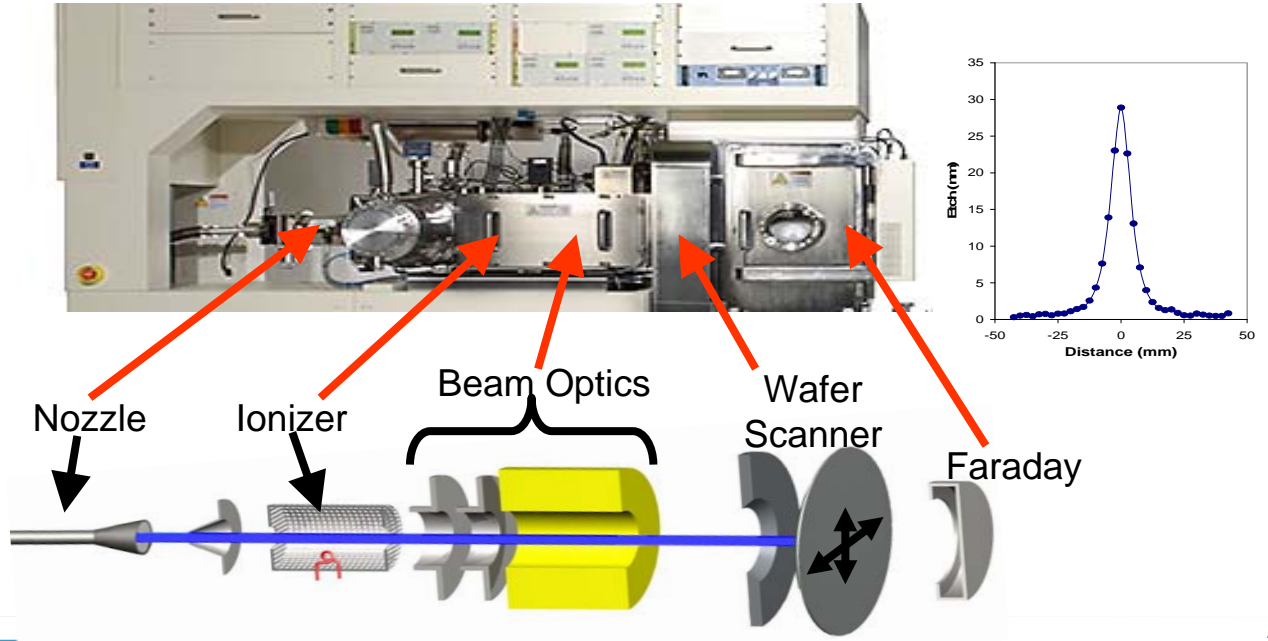
**Nate Baxter**  
TEL-Epion  
Semicon West 2008  
AVS WCJUG

# Outline

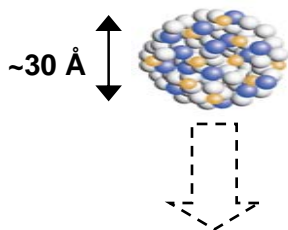
- **Gas Cluster Ion Beam Introduction**
- **GCIB USJ Doping**
- **Defects**
- **Activation Enhancement**
- **Conclusion**



# Infusion: Gas Cluster Ion Beam Processing

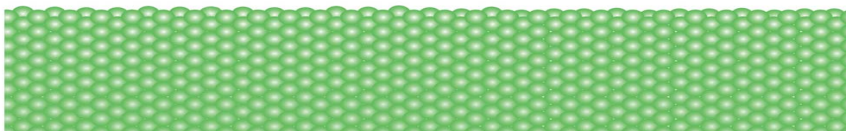


# Infusion: Gas Cluster Ion Beam Processing



Almost any mix of gaseous species

- $B_2H_6$ ,  $PH_3$  for doping
- $SiH_4$ ,  $GeH_4$ ,  $NH_3$ ,  $CH_4$ ,  $N_2$ ,  $Ar$ ,  $O_2$  for surface modification or film deposition
- $NF_3$ ,  $CF_4$  for etching



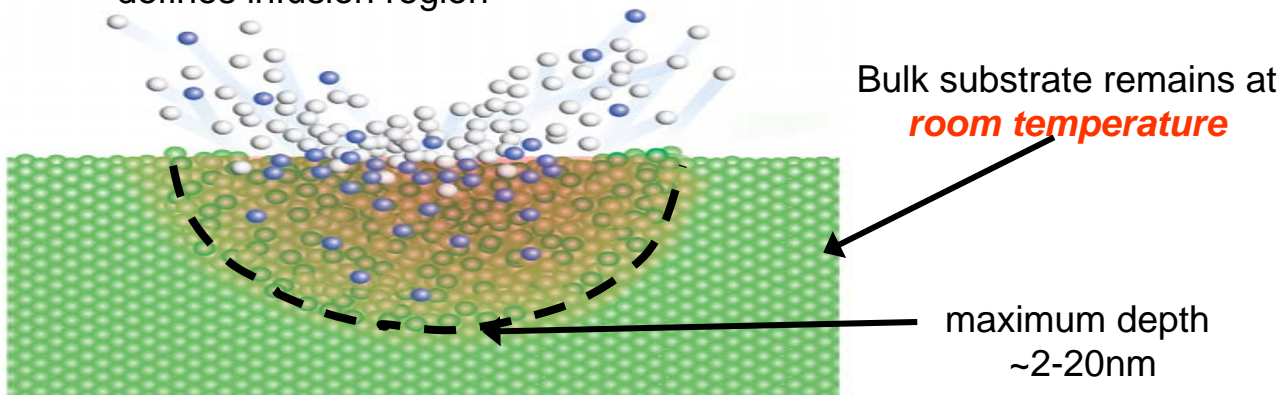
During transport, clusters have:

- High total energy (many kV)
  - Leads to extreme chemical and physical reactions at the substrate
- Low energy per molecule (<5eV)
  - No atom penetrates deeply into the substrate

# Gas Cluster / Surface Interaction

## Upon Impact

- Cluster immediately dissociates
- Transient (<10psec) thermal and pressure spike defines infusion region



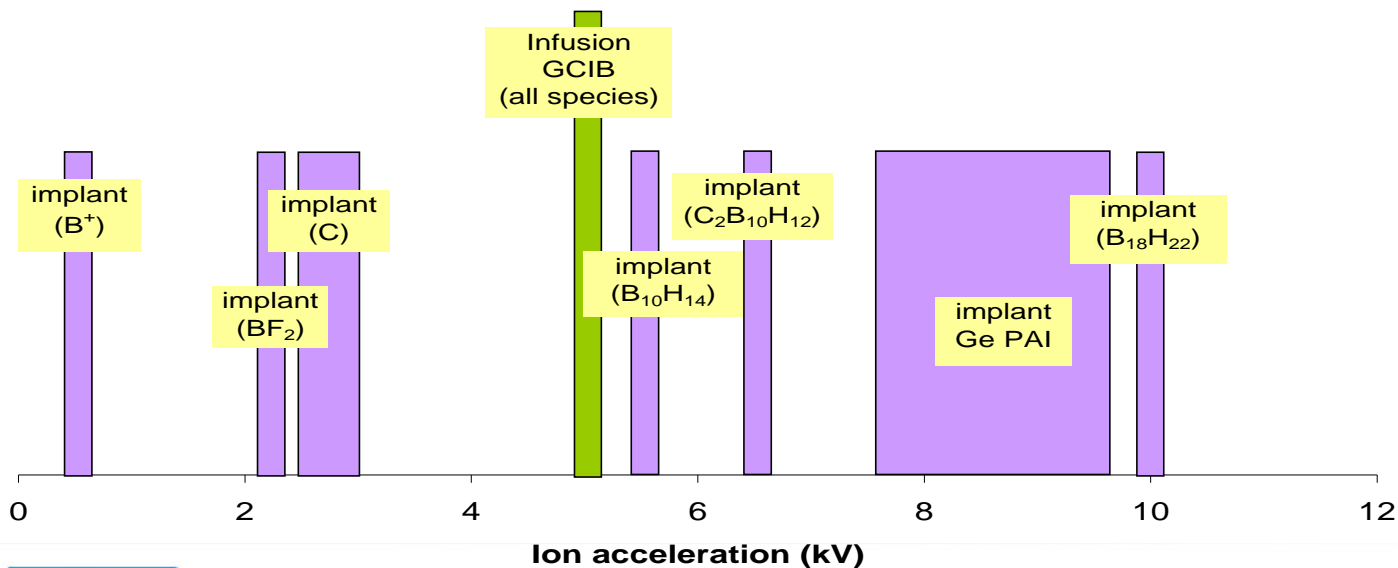
**The cluster/substrate interaction is unique**  
**Infusion achieves process results not possible by conventional techniques**  
**(Different from ion implantation and plasma process)**

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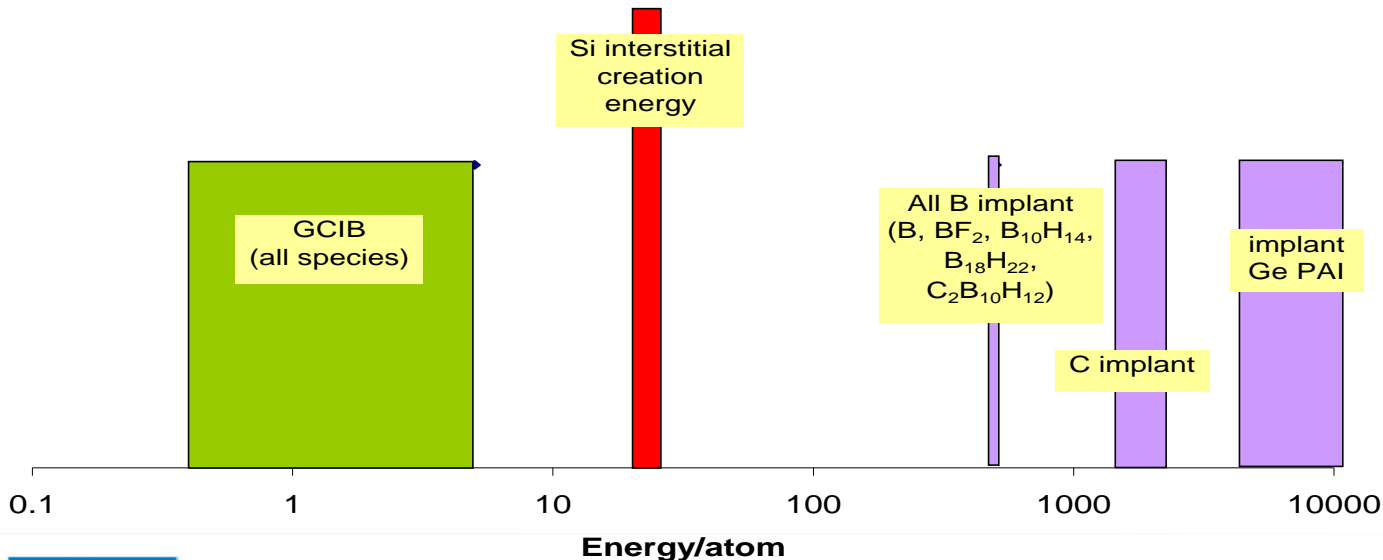
# USJ doping energies for Xj ~10nm

## (Ge PAI + B 500eV)



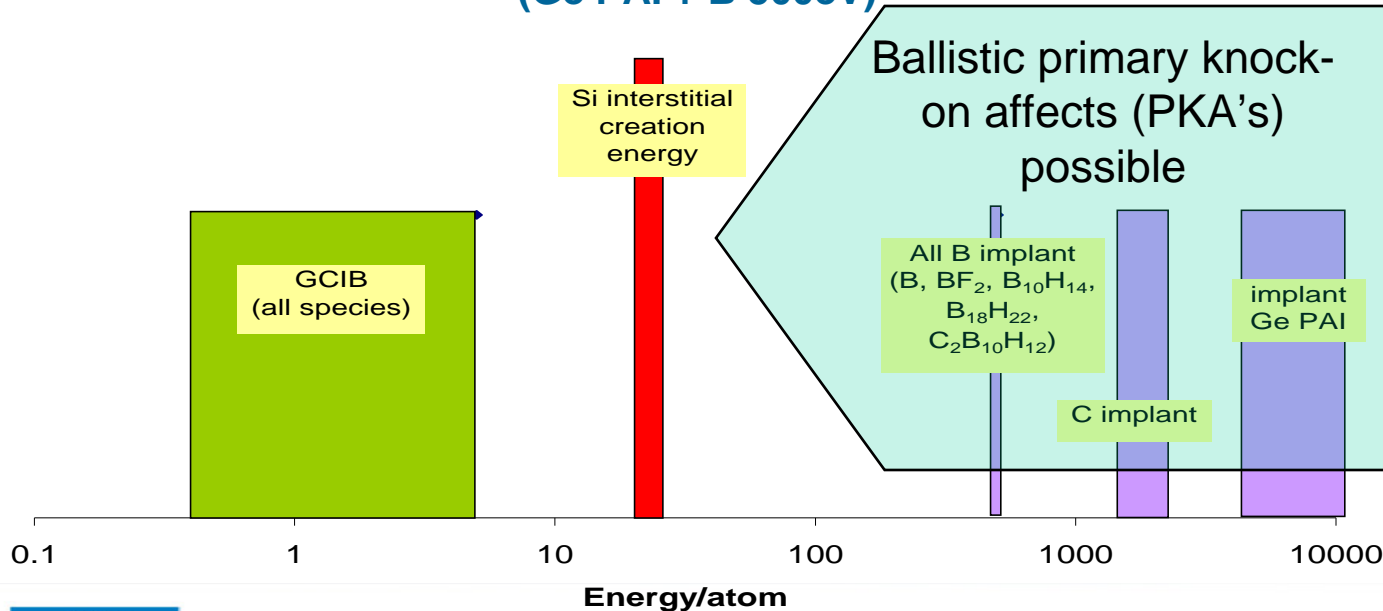
# USJ per atom doping energies for $X_j \sim 10\text{nm}$

(Ge PAI + B 500eV)

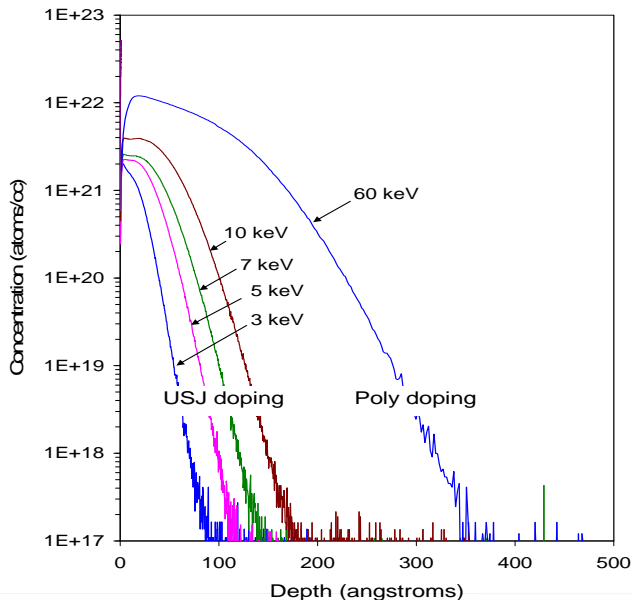


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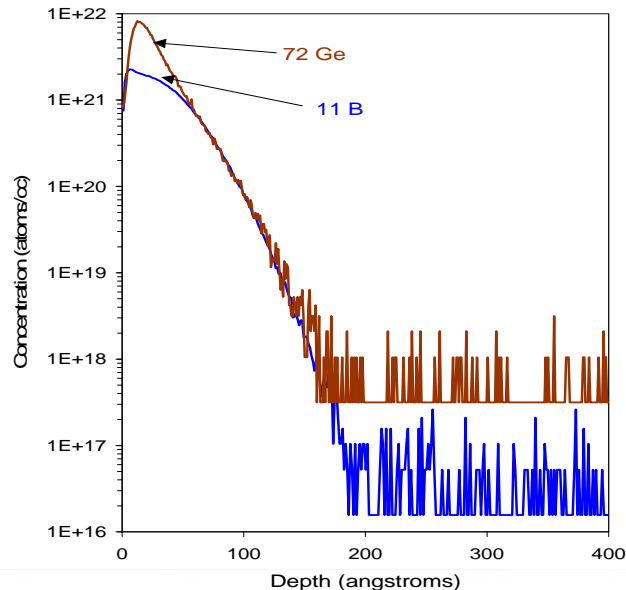
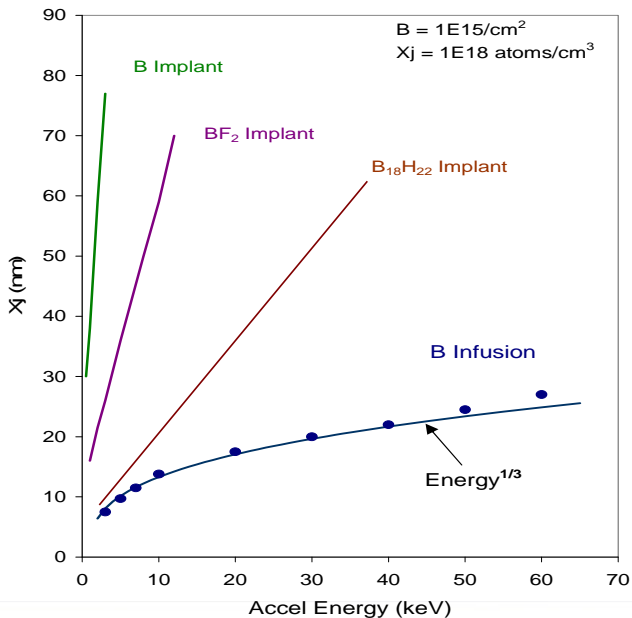


# Infusion doping for USJ

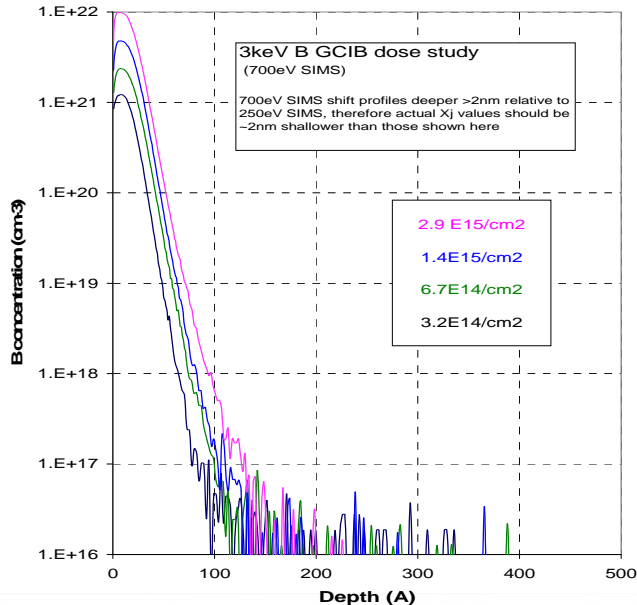
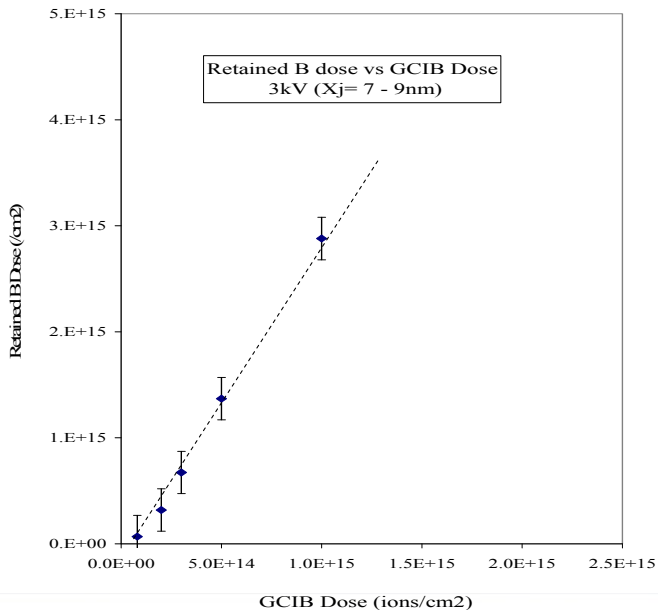


- Abrupt box-like profiles
  - Improved SCE
- Low energy (<5eV) per atom
  - No channeling
  - No beam angle effects or straggle.
  - Improved Vt spread.
- Low power (<1W)
  - No wafer level thermal effects
- Fully self amorphizing by localized thermal (non-ballistic) events
  - No evidence of EOR damage
  - Improved leakage performance

# GCIB doping depth scales with $E^{1/3}$ and is mass independent



# Self-sputtering test for ultra shallow GCIB: Linear Relationship GCIB Dose vs Retained Dose

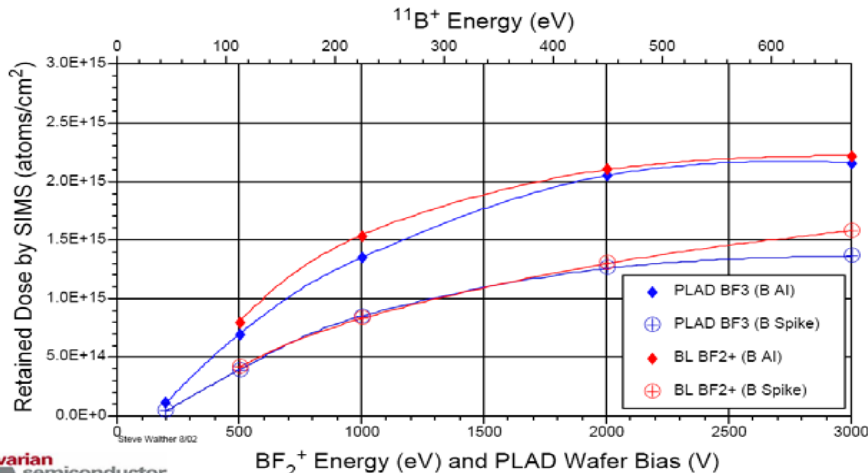


# Ion implant Self-Sputtering limitations

As-implanted (3E15) and Spike Annealed



Equivalent dose control and retention over energy range

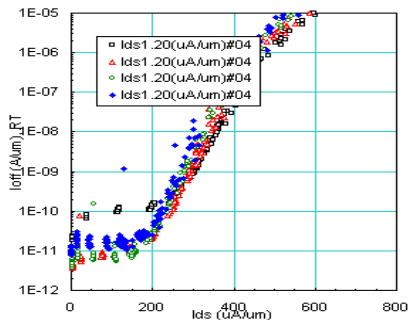


From IIT 2002

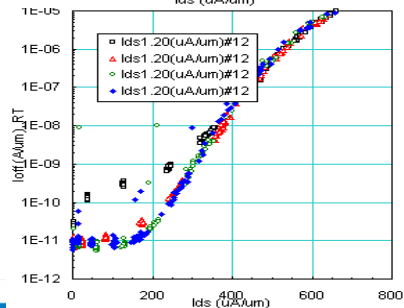
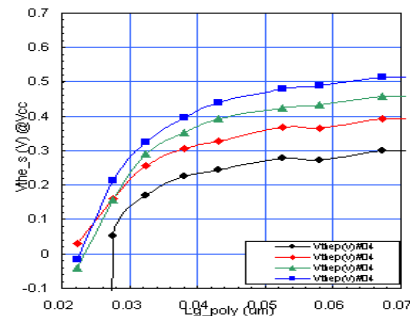
°C, 200 °C/s, Spike Anneal, AST 3000



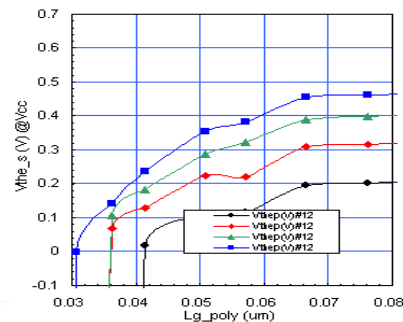
# USJ Boron Doping: Device Lots



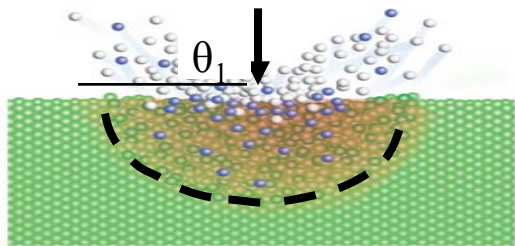
Infusion: 5kV 1%B2H6/Ar



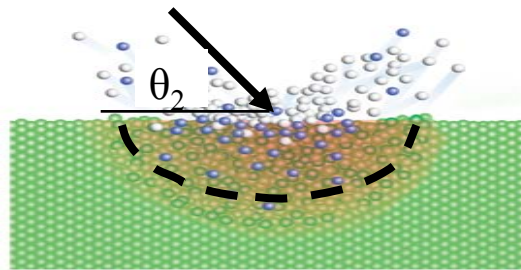
Implant: 0.2keV 1.0E+15 B



## Non-ballistic process means no angular variation effects (improved lateral abruptness) for improved $V_t$ spread.



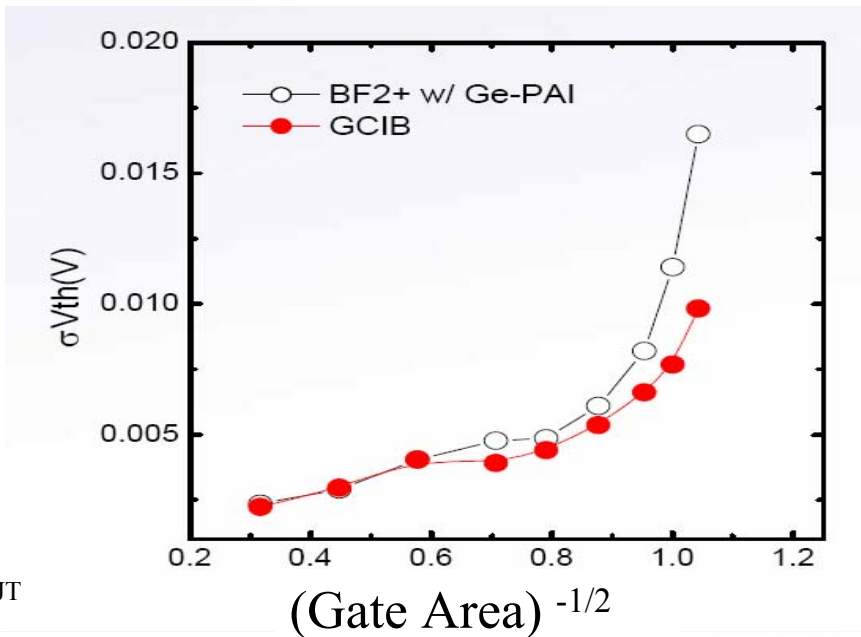
Individual B energy  $\sim 1\text{eV}$ , therefore depth is determined exclusively by the collective cluster energy transferred to the Si surface. No straggle possible.



The lack of energetic ballistic B means there will be no angular component to the B infusion.

Any variations in beam angle will have no changes in overlap control or skew.

# Vt spread



Ho Lee, Samsung, 2006 IWJT



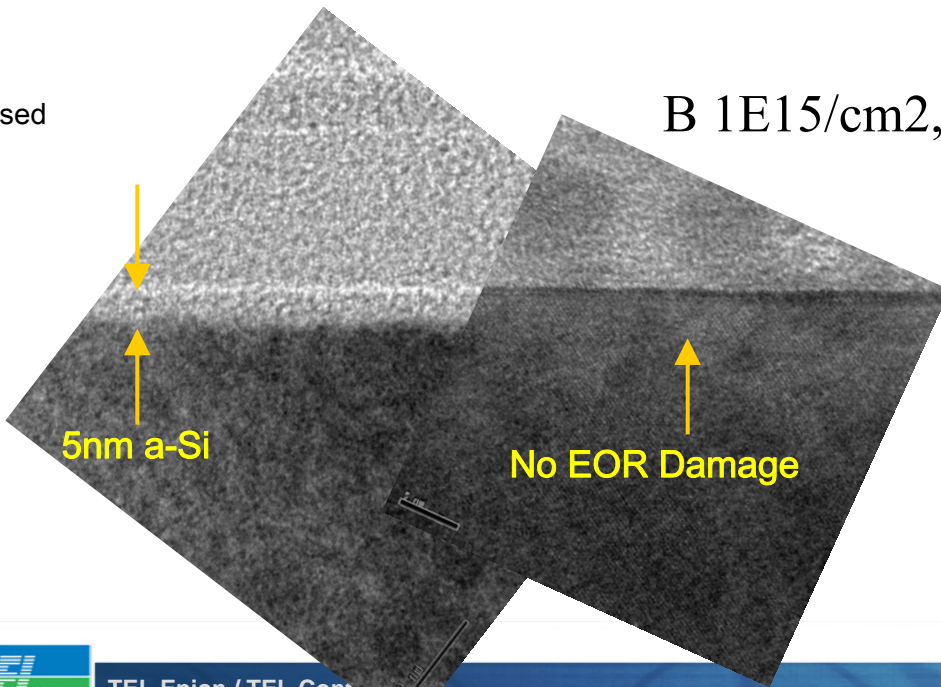
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# EOR test

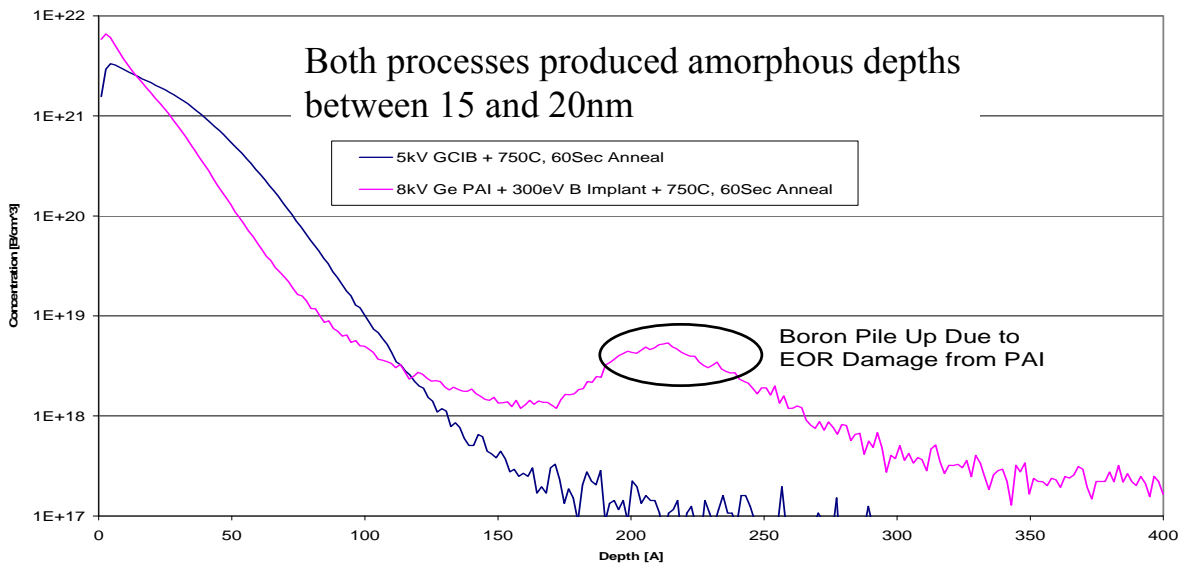
As-infused

B 1E15/cm2, 10nm Xj

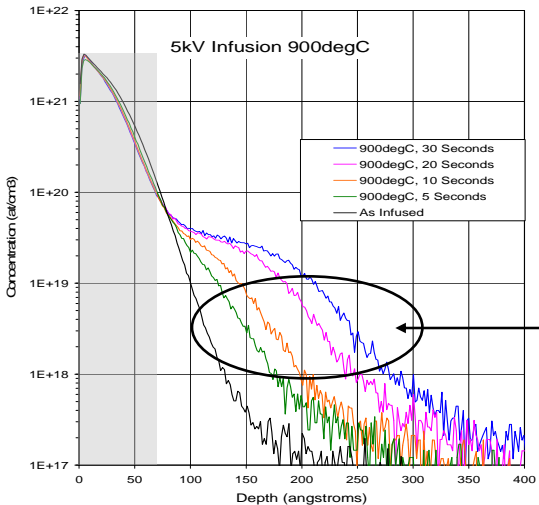


Post anneal

# EOR pile up test

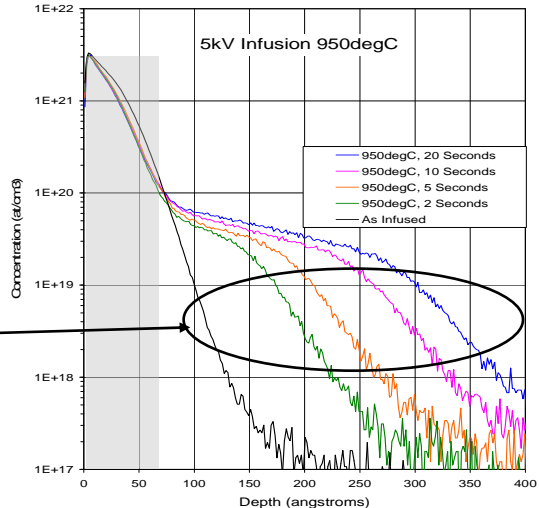


# EOR / TED test



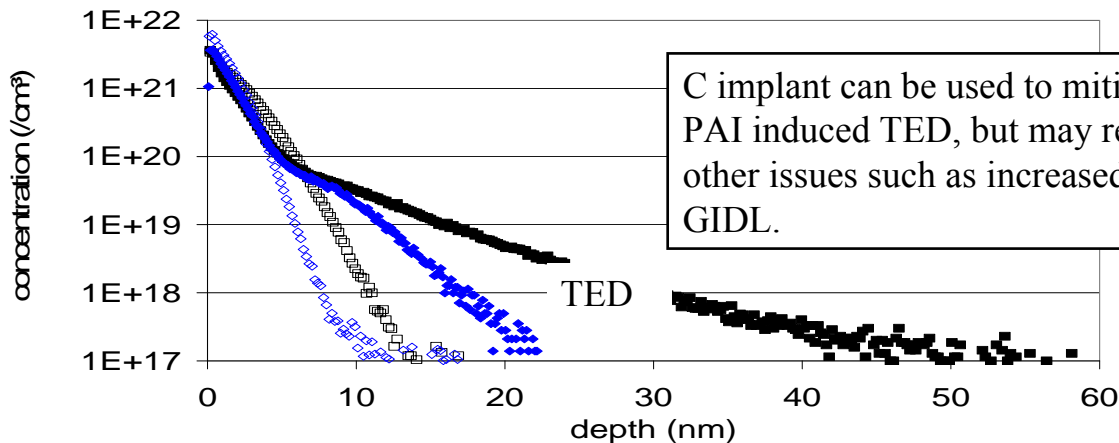
Self-amorphized  
depth

No evidence of  
TED



# EOR / TED test

□ as-implanted BF2 w/Ge PAI    ■ implanted; 950°C anneal  
 ◇ as-infused    ◆ infused; 950°C anneal



No EOR interstitials generated by GCIB → No TED → No C required → **Improved GIDL**

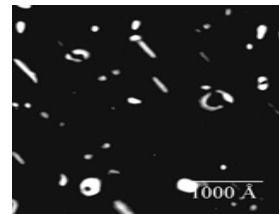
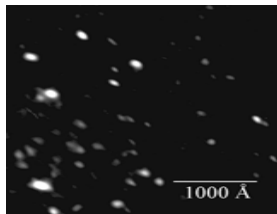
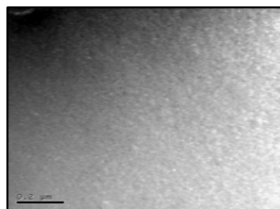
# Plan view TEMs

## Infusion

## Implant

Flash temperature:  
1200°C      1350°C

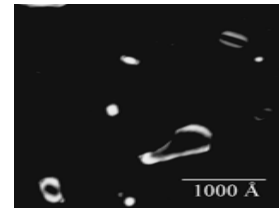
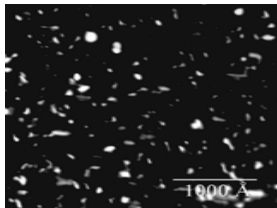
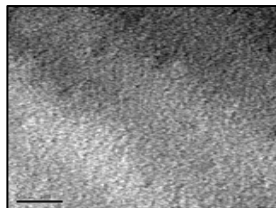
900C, 30 Sec



Intermediate  
temperature:

800°C

1350C Flash  
1000C intermediate



900°C

Amitabh Jain, *Mat. Res. Soc. Symp. Proc. vol. 810, C5.6.1, 2004.*



# Leakage comparison

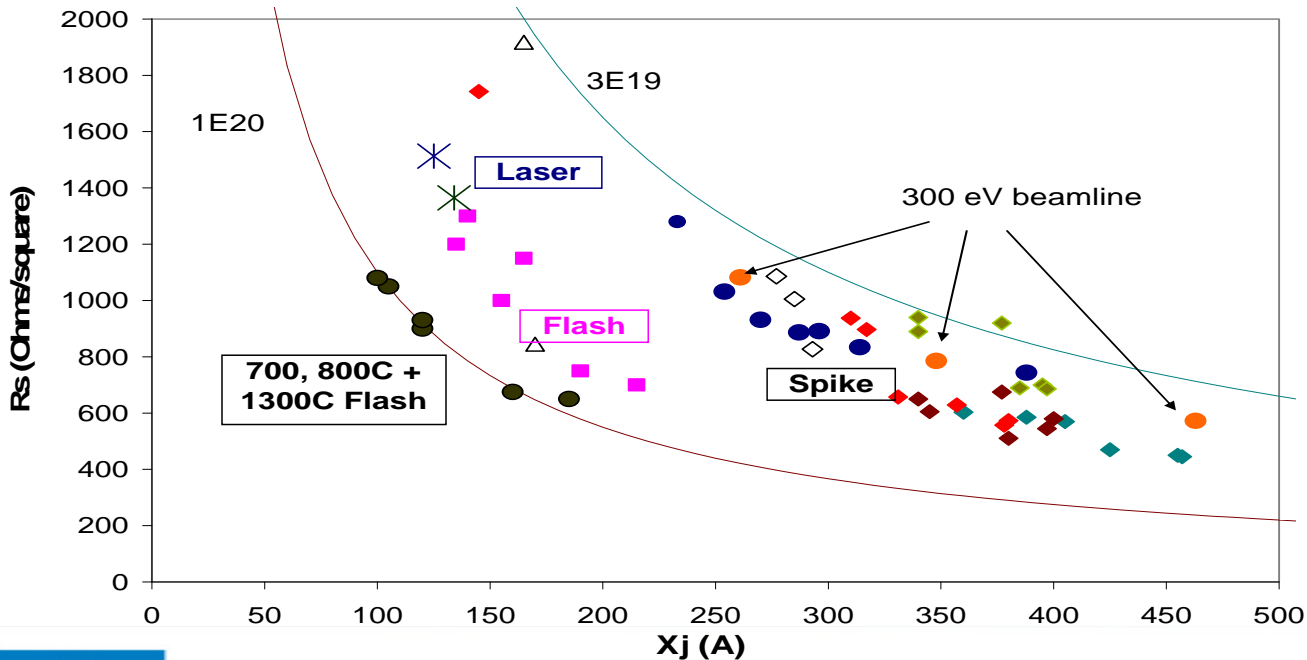
Doping condition	Anneal	Rs Measurement ( $\Omega/\text{sq}$ )		Leakage I ( $\mu\text{A}/\text{cm}^2$ )	Xj @ $1\text{E}18$ ( $\text{\AA}$ )
		4 PP	RsL		
GCIB	Laser	2076	2103	<b>0.1</b>	125
GCIB	450 °C 1 hour + Laser	1513	1547	0.437	125
20kV Ge PAI + 2kV C + GCIB	Laser	1365	1299	<b>1.475</b>	135

1. The addition of PAI + C implants + laser anneal increases leakage as compared to GCIB + laser anneal alone.
2. Adding a VLTA pre-laser anneal to GCIB doping significantly improves activation.
3. Adding a VLTA pre-laser anneal to GCIB doping exhibits increased leakage..

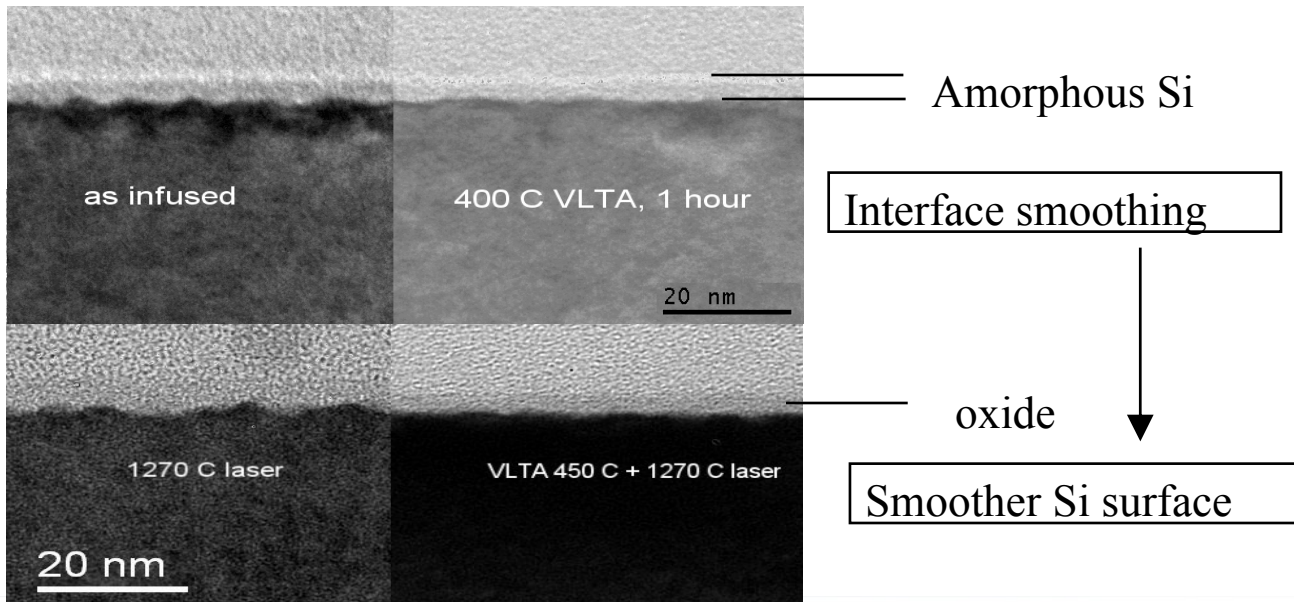
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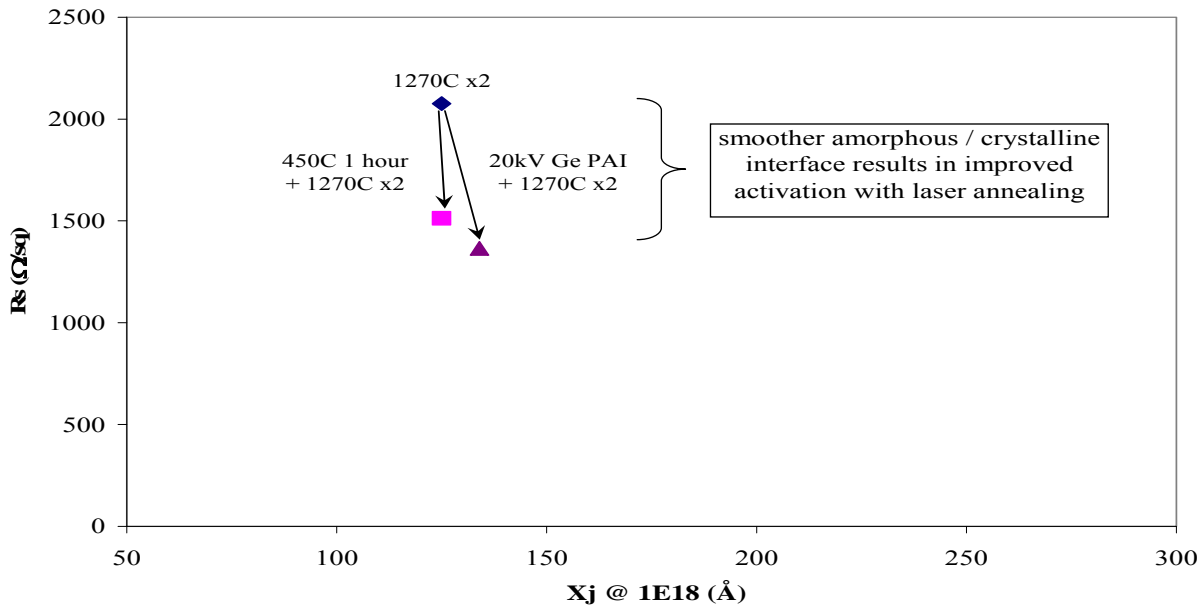
# GCIB B activation studies



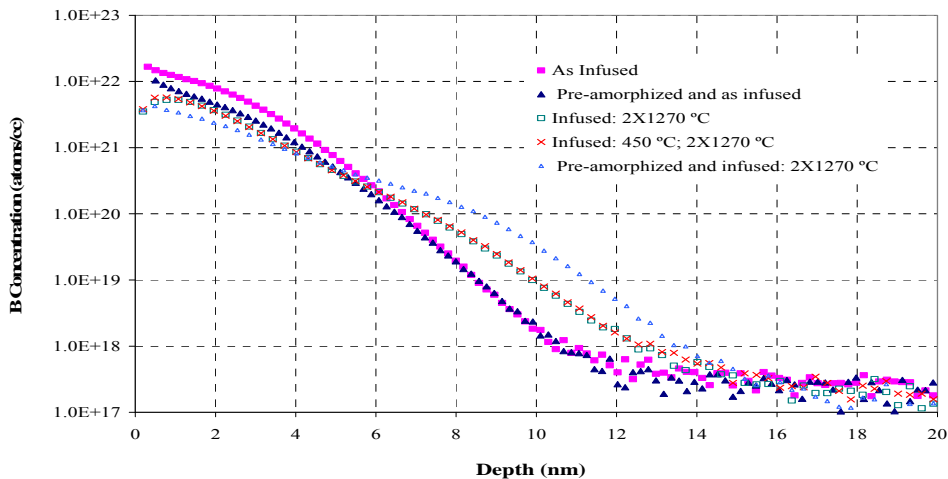
# Interface smoothing by VLTA



# Interface smoothing improves activation



# Interface smoothing tests : SIMS



1. GCIB infusion into crystalline or pre-amorphized Si show same doping profile.

2. VLTA pre-anneal does not affect the diffused profile.

3. Ge PAI + C implants enhance B diffusion.

# Conclusions

- **GCIB doping is a shallow self-amorphizing low energy per atom process.**
  - Abrupt profiles produced without Ge PAI (C implant)
- **GCIB doping is not implantation (ballistic)**
  - Channeling or straggle not possible.
    - *Improved  $V_t$  sigma*
  - No Si interstitial defect pile-up at EOR observed
    - *No TED observed*
    - *Lower leakage is observed when compared to Ge PAI+C implanted sample.*
- **GCIB USJ formation requires hybrid anneals for optimal activation**
  - Initial data suggests VLTA improves activation but will require further optimization to reduce leakage.

# Acknowledgements

- Yan Shao – TEL Epion
- John Hautala – TEL Epion
- Larry Larson – Sematech FEP Division
- Amitabh Jain – Texas Instruments, Advanced CMOS



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